

3A Avg.

65 Volts

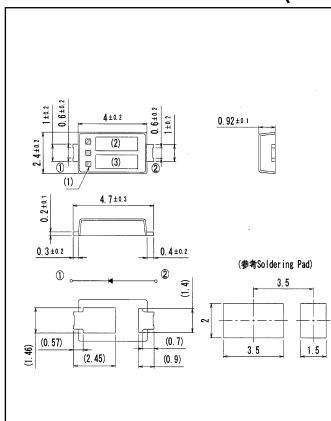
SBD

NA03QSA065

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	65	V
平均整流電流 Average Rectified Forward Current	I_O	$T_a=27^{\circ}\text{C}^*$ $V_{RM}=30\text{V}$	1.3
		$T_l=117^{\circ}\text{C}$ Tl:lead Temperature $V_{RM}=30\text{V}$	3.0
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	4.71	A
サージ順電流 Surge Forward Current	I_{FSM}	60 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}\text{C}$

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.03 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}$, $V_{RM}=65\text{V}$	—	—	300	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}$, $I_{FM}=3\text{A}$	—	—	0.61	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	130	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	13	$^{\circ}\text{C}/\text{W}$

*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm)

■定格・特性曲線

